



IFW

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Filippi et al.

Examiner: Quoc Dinh Hoang

Serial No: 10/815,418

Group Art Unit: 2818

Filed: April 1, 2004

Docket: YOR20040086US1 (163-32)

For: CONTROL OF LINER THICKNESS FOR IMPROVING  
THERMAL CYCLE RELIABILITY

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450,  
Alexandria, VA 223131-1450

**RESPONSE TO OFFICE ACTION**

**SETTING FORTH A RESTRICTION REQUIREMENT**

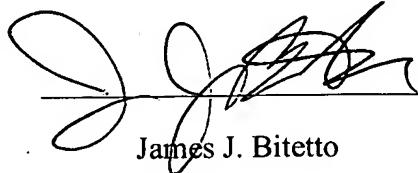
Sir:

In response to the Office Action mailed June 29, 2005, Applicants hereby elect to prosecute the claims directed to Group II drawn to a method for evaluating reliability of a semiconductor chip, i.e., claims 1-15. Applicants make the present election with traverse.

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**CERTIFICATE OF MAILING 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence (and any document referred to as being attached or enclosed) is being deposited with the United States Postal Service as first class mail, postage paid in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 223131-1450 on 7/19/05.

 7/19/05  
James J. Bitetto